

Fig.1

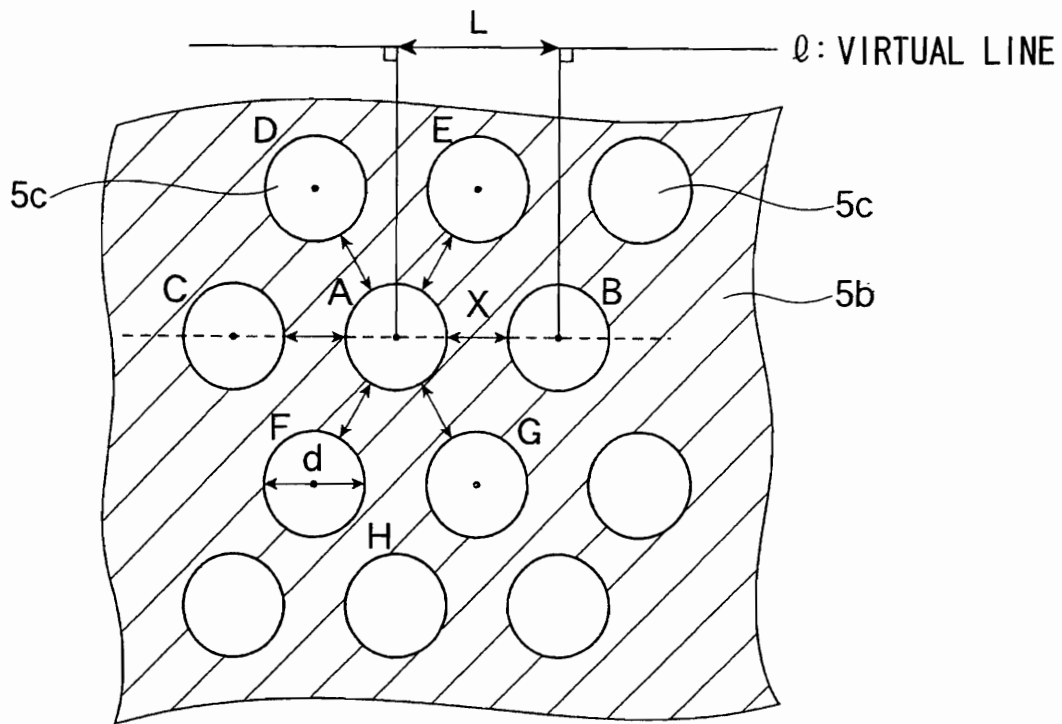


Fig.2

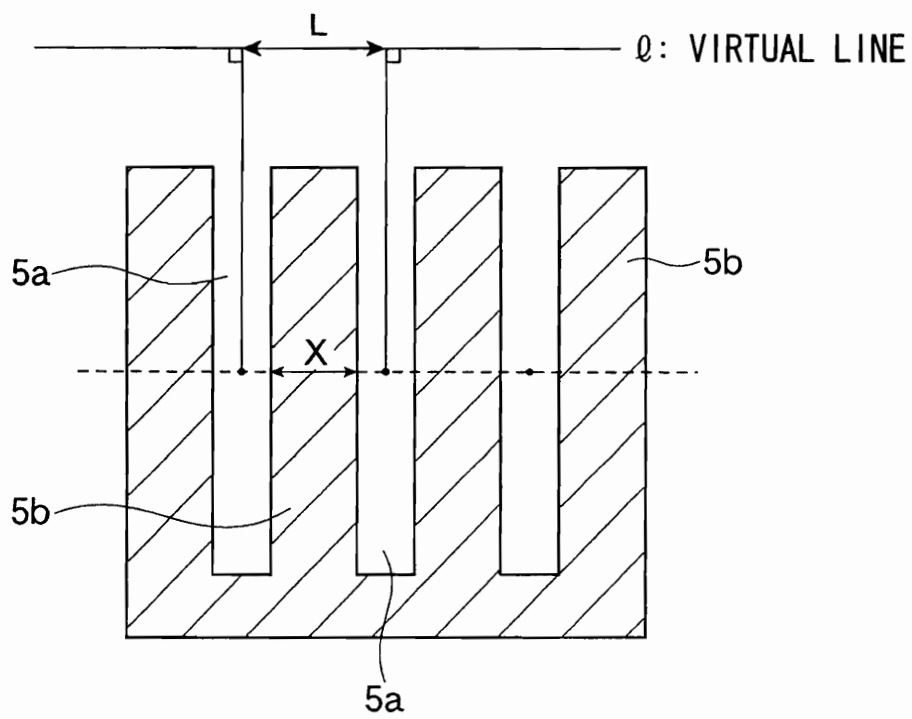


Fig.3

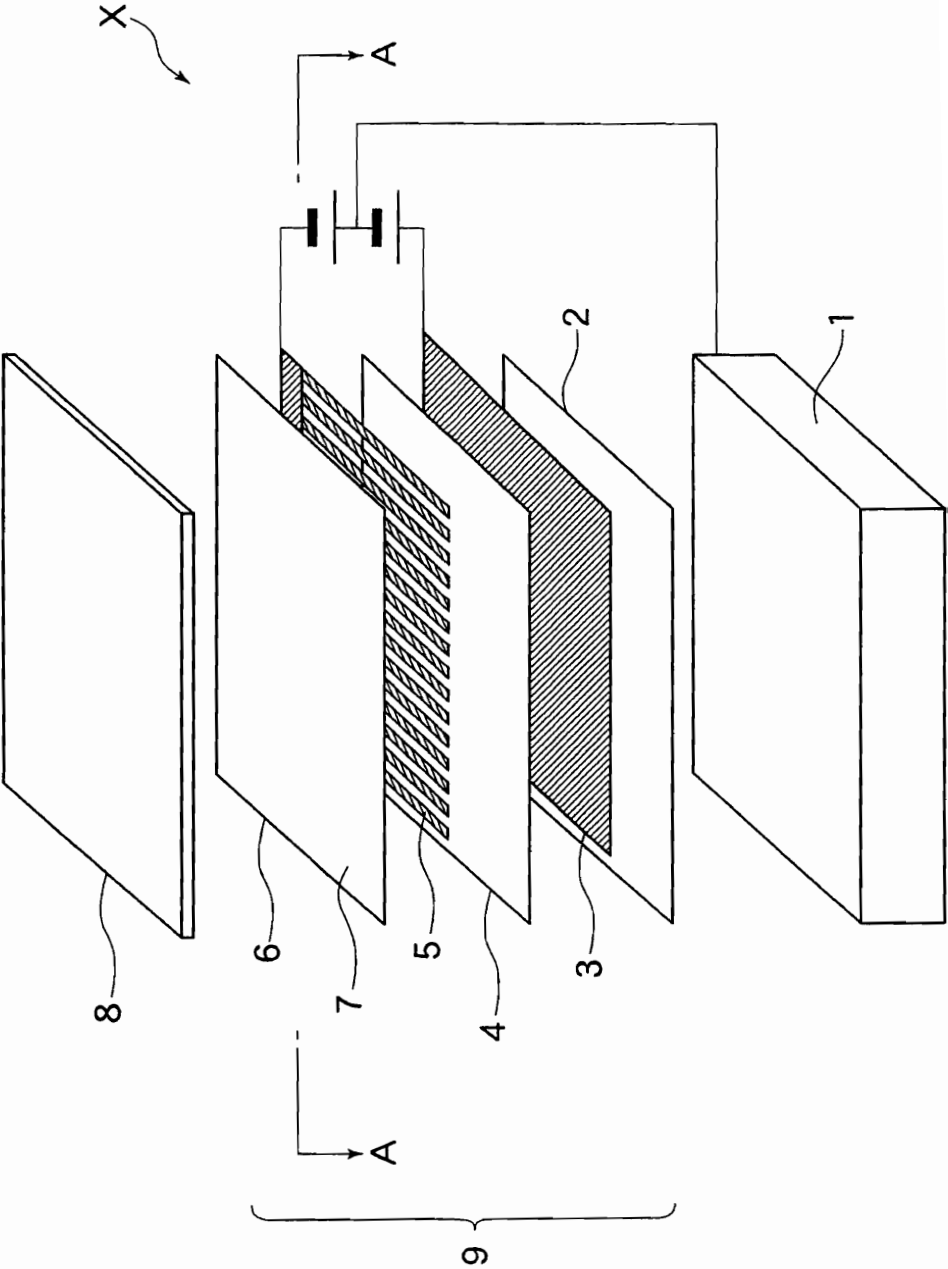


Fig.4

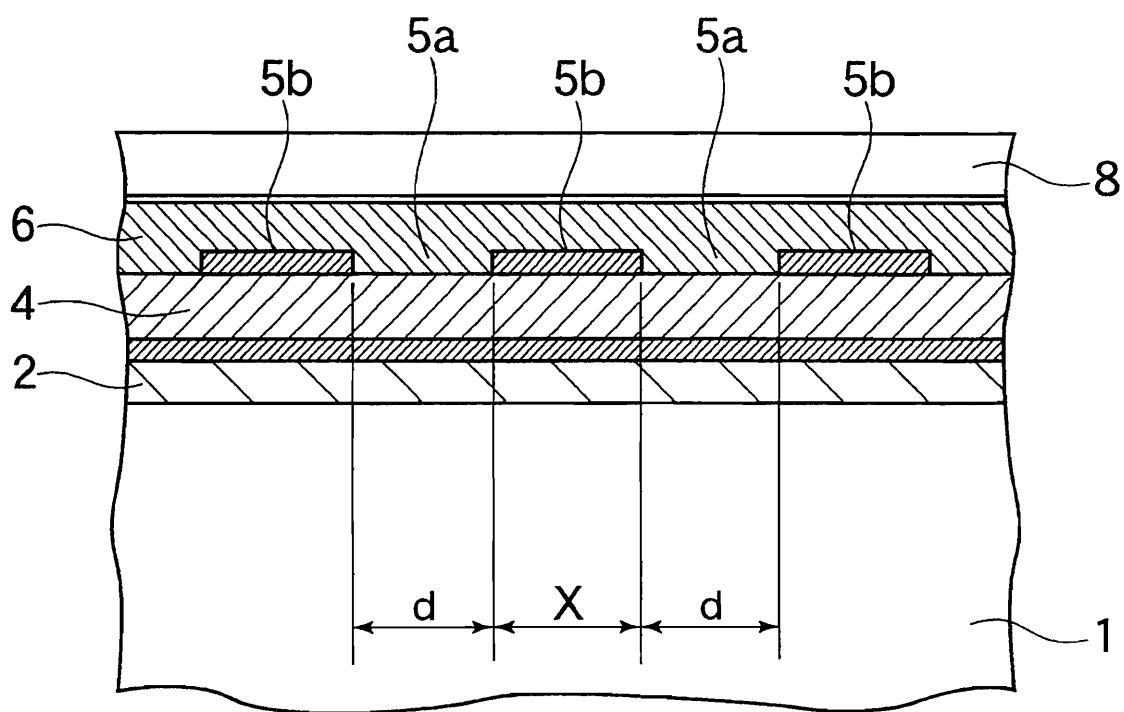


Fig.5

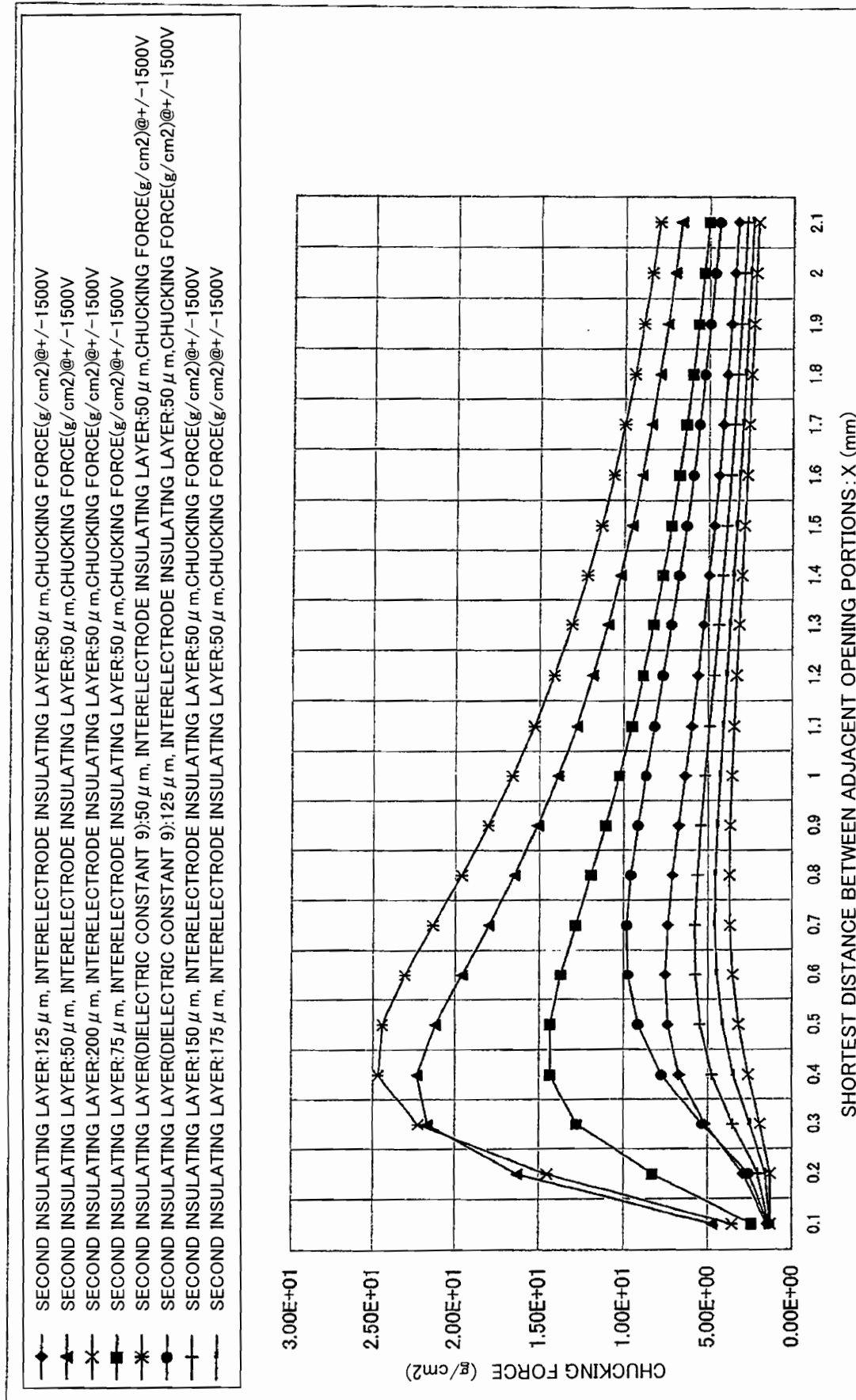


Fig.6

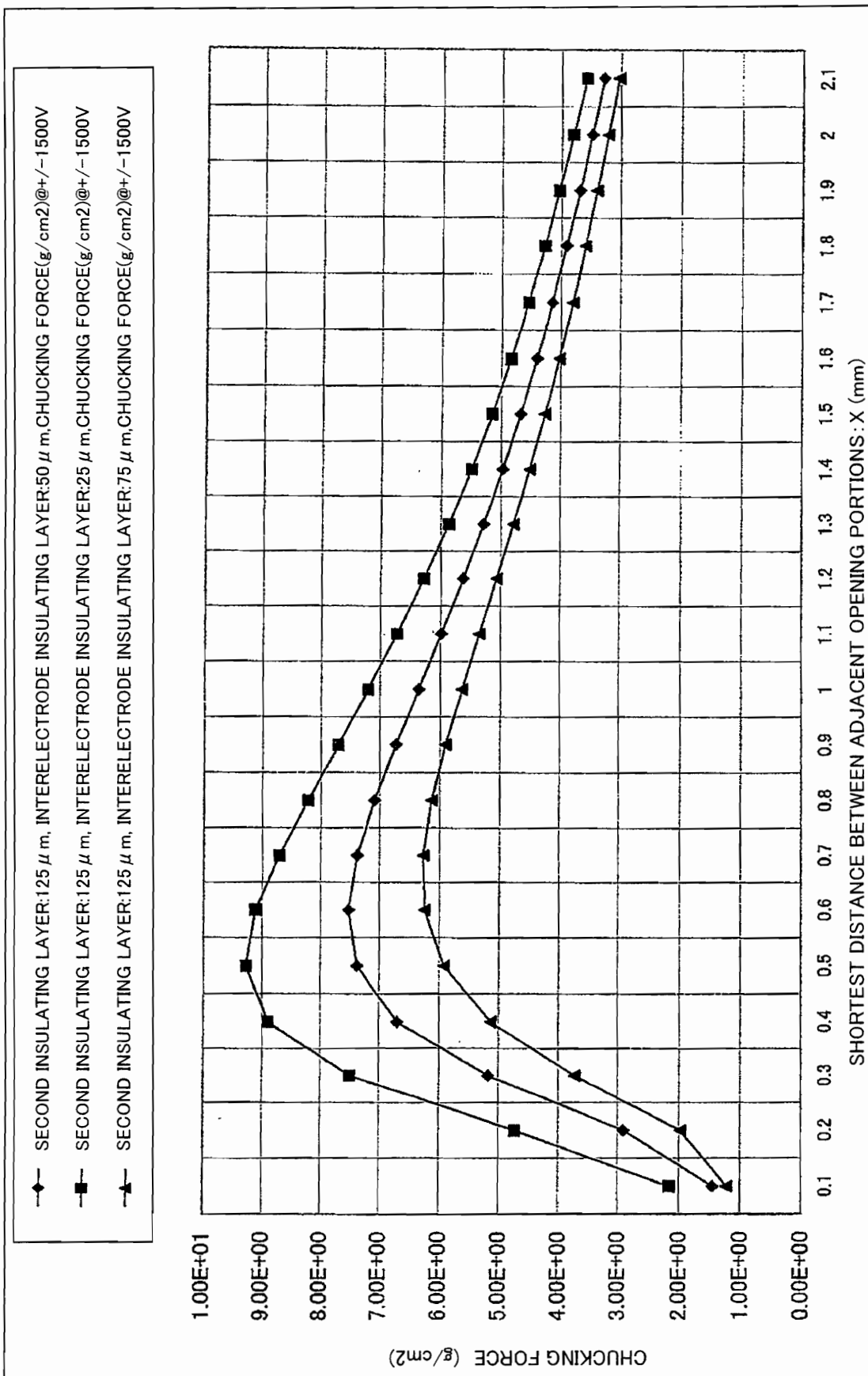


Fig.7

- CIRCULAR HOLES, SECOND INSULATING LAYER:125 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- ▲— CIRCULAR HOLES, SECOND INSULATING LAYER:50 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- ◆— CIRCULAR HOLES, SECOND INSULATING LAYER:200 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- ×— CIRCULAR HOLES, SECOND INSULATING LAYER:75 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- *— CIRCULAR HOLES, SECOND INSULATING LAYER:DIELECTRIC CONSTANT 9;125 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- CIRCULAR HOLES, SECOND INSULATING LAYER:DIELECTRIC CONSTANT 9;50 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- +— CIRCULAR HOLES, SECOND INSULATING LAYER:150 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V
- CIRCULAR HOLES, SECOND INSULATING LAYER:175 μ m, INTERELECTRODE INSULATING LAYER:50 μ m,CHUCKING FORCE(g/cm2)@+/-1500V

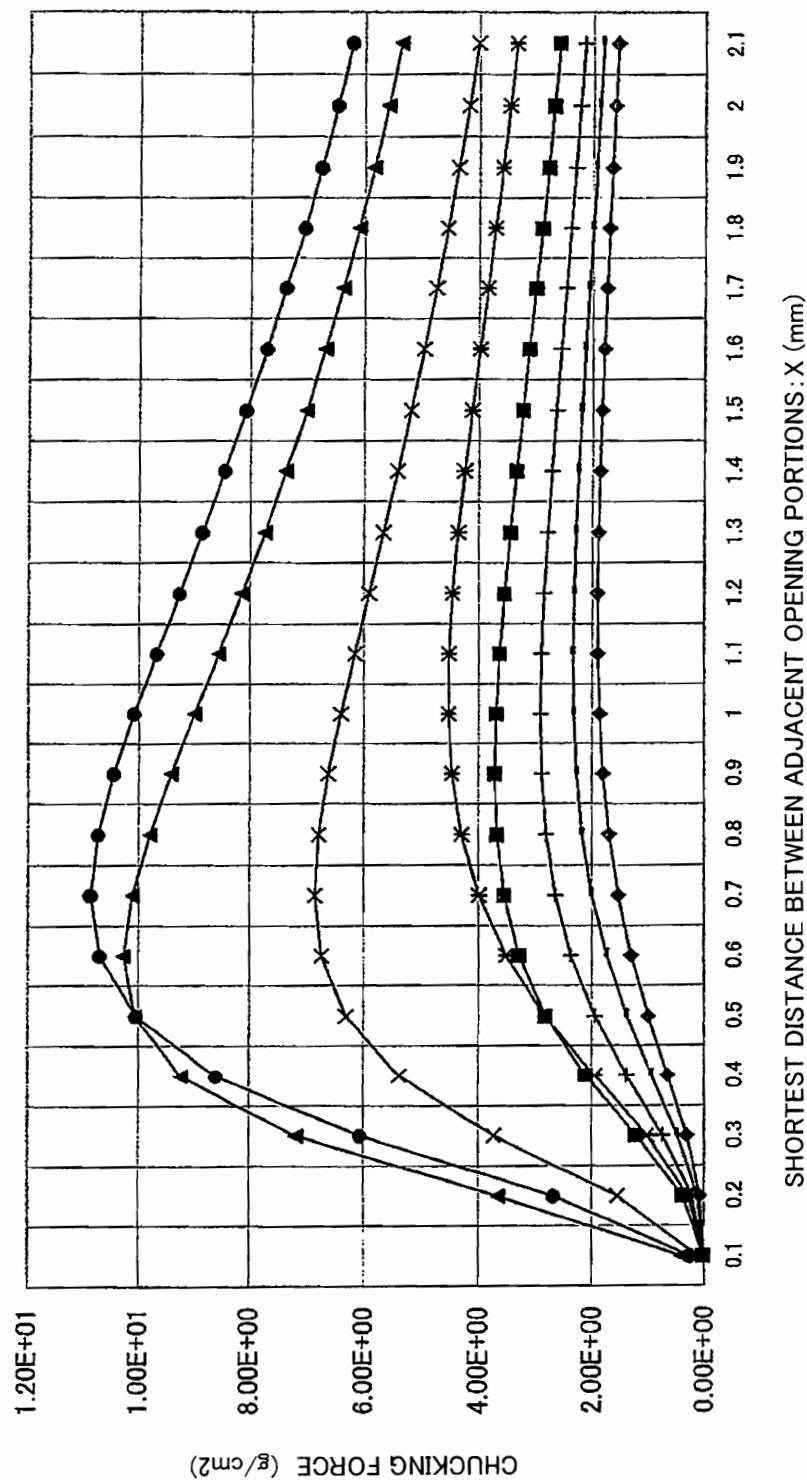


Fig.8

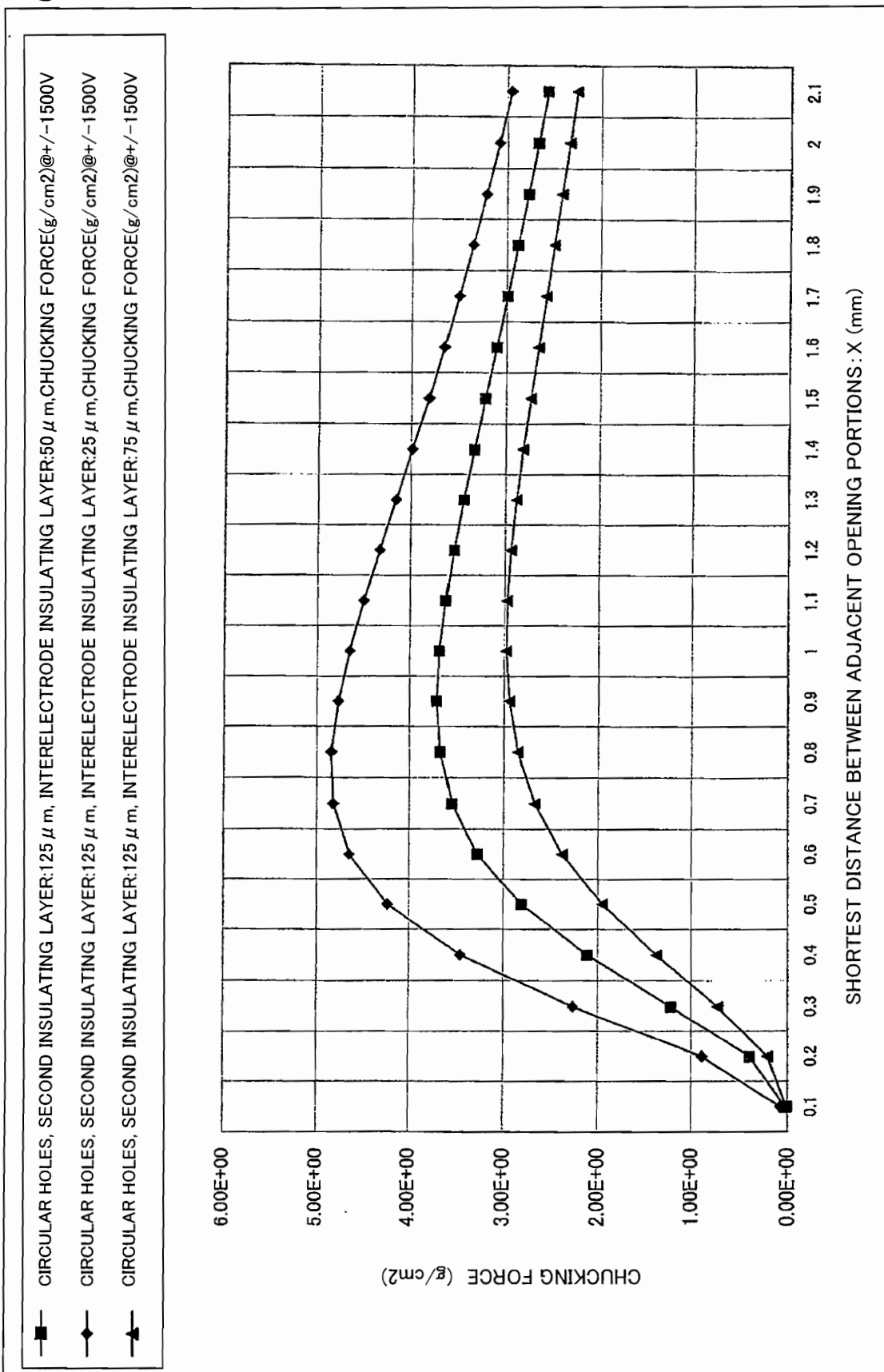


Fig.9

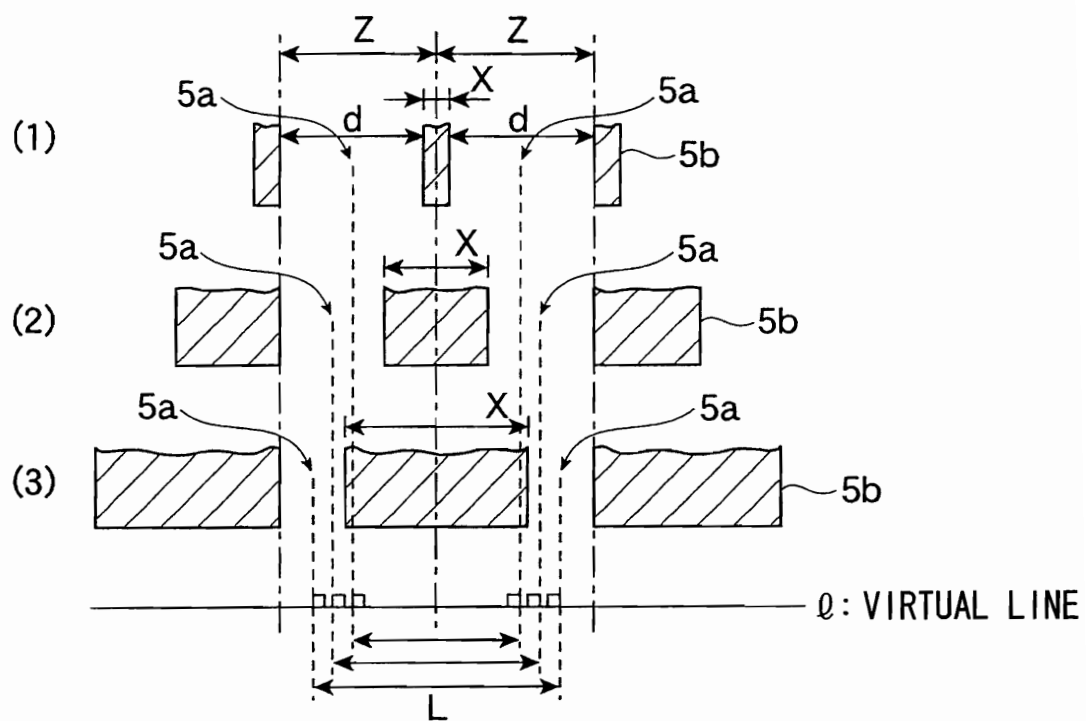


Fig.10

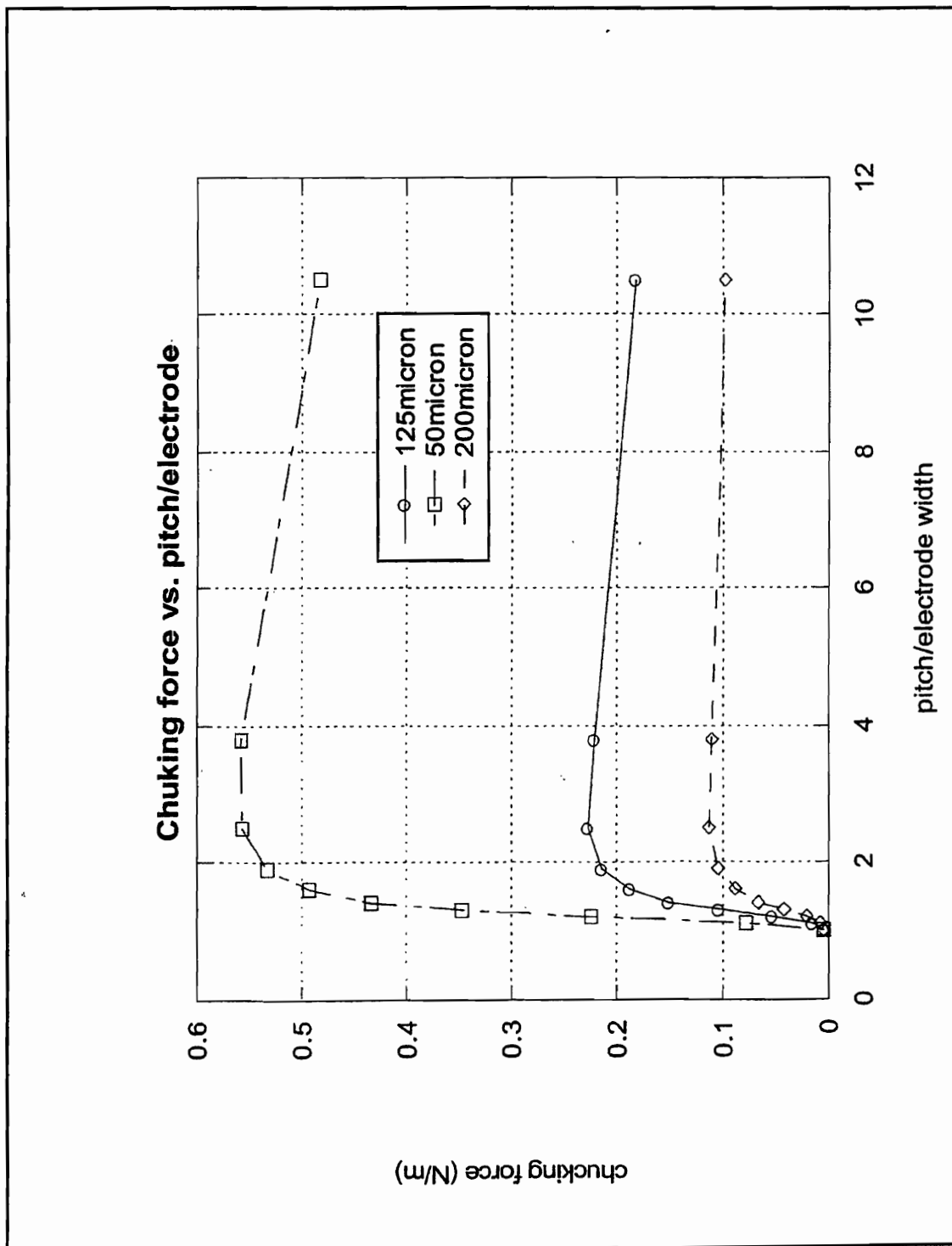


Fig.11

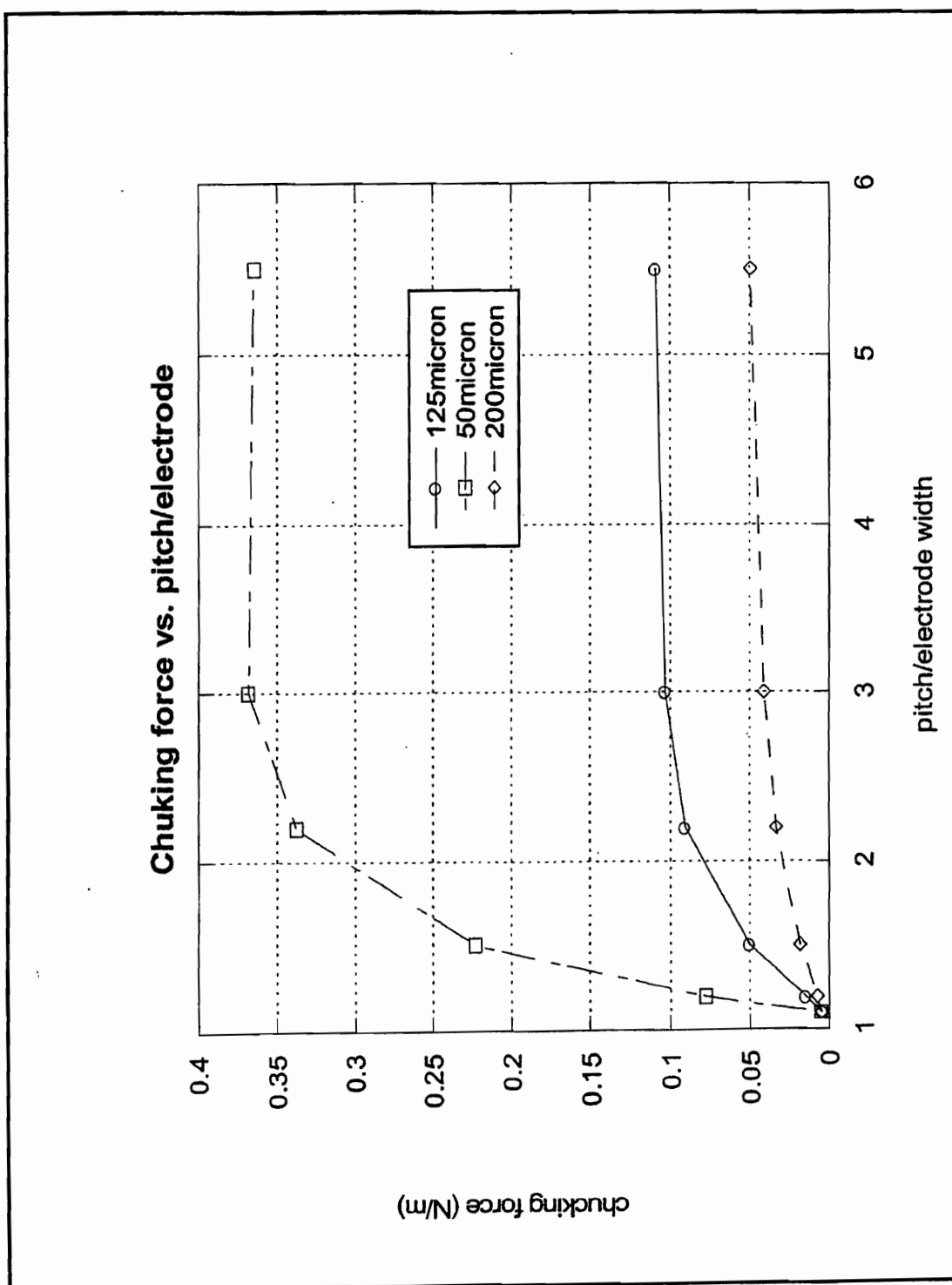


Fig.12

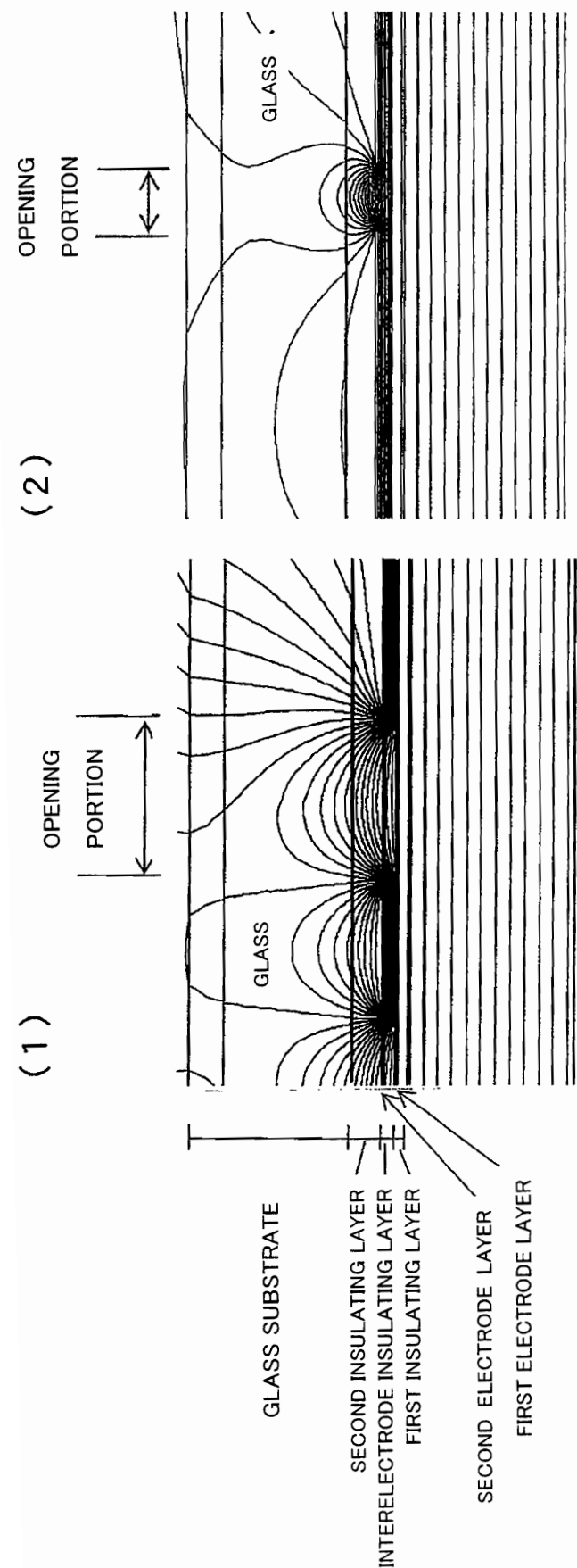


Fig.13

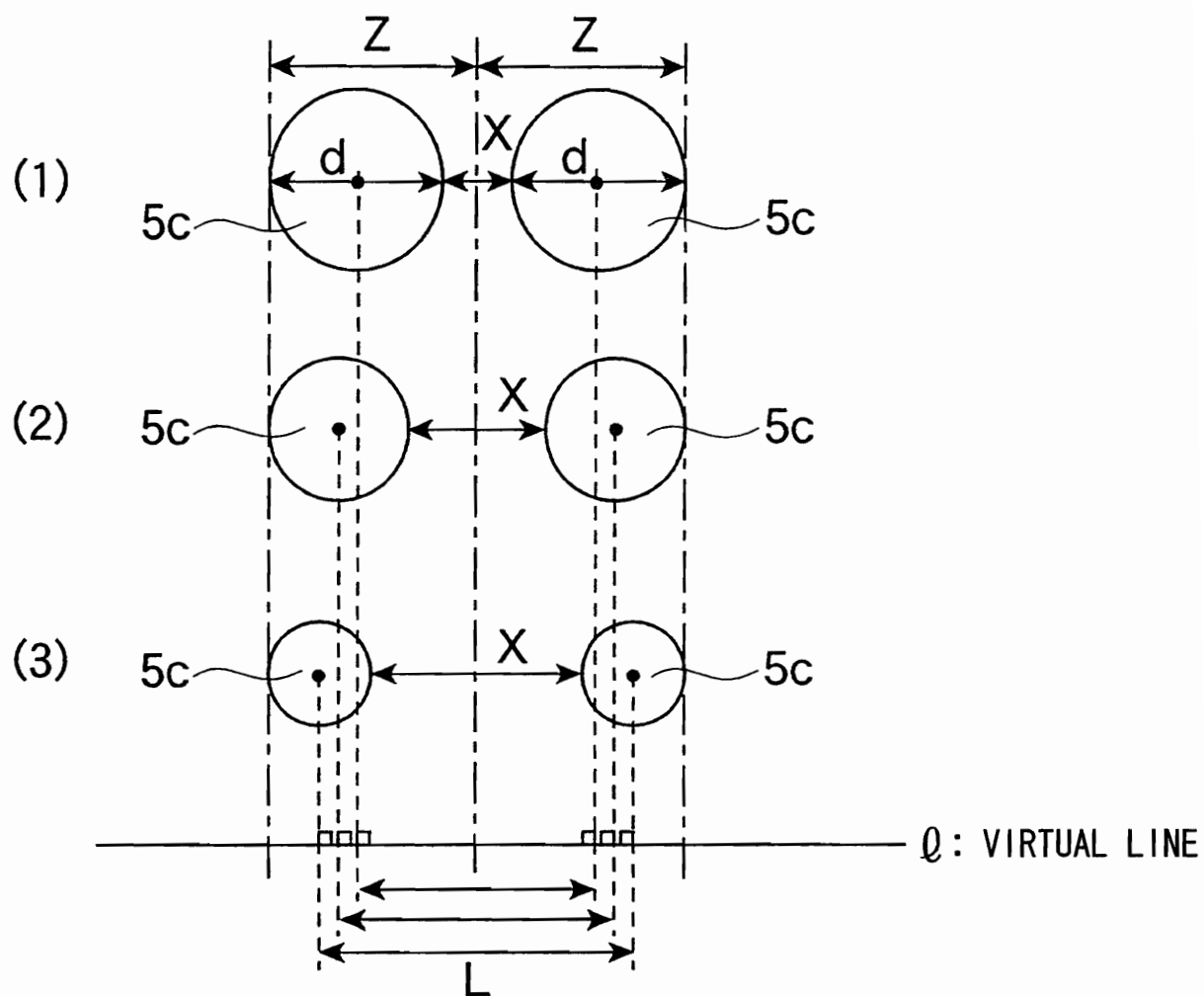


Fig.14

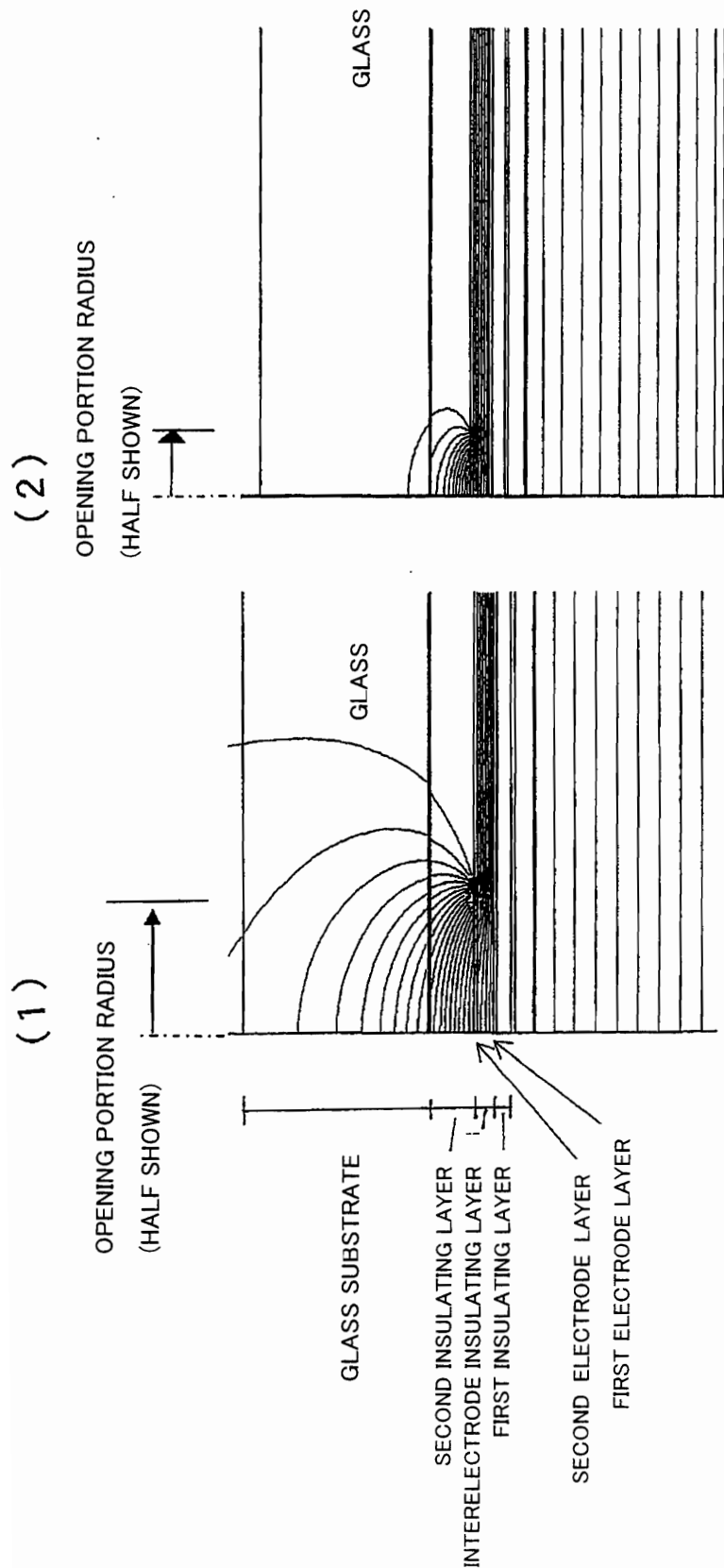


Fig.15

